

Overview

The purpose of this notification is to communicate a change in the wafer fabrication and sort facility for all devices in the Platform Flash (XCF) and XC18V00 families of flash memory configuration PROMs devices. This notification does not apply to the Platform Flash XL (XCF128X) device. Note that this notification applies to Commercial (C) temperature grade products only. There is no change to the fit or function of these devices. The form of these devices is changing with topside marking changes only.

Description

Production of all Platform Flash and XC18V00 families with the STMicroelectronics "T7Y" 150nm manufacturing process will transition from the STMicroelectronics M5 wafer fabrication facility in Catania, Italy to the Numonyx Fab2 wafer fabrication facility in Singapore (Table 1).

Table 1: **Fabrication Facility Location Change Summary**

| Xilinx Family | Change Description |
|----------------|--|
| Platform Flash | Wafer Fabrication and Sort Facility Changes from "M5" to "Fab2" Facility |
| XC18V00 | Wafer Fabrication and Sort Facility Changes from "M5" to "Fab2" Facility |

This change will improve the ability of Xilinx to support these products effectively and to accommodate high-volume demand. There is no change in process technology associated with this notification. The same Numonyx T7Y 150nm manufacturing process is used at both the M5 and Fab2 facilities. The fit and function of devices manufactured at Fab2 and M5 facilities will be the same. The form of these devices is changing with topside marking changes only. There is no change to the device IDCODE (the IDCODE revision for Fab2 has been changed to D for wafer fab identification purposes). Xilinx iMPACT software and recommended third party programming software will not be affected by this change.

Products Affected

This change affects all standard and SCD part numbers for Platform Flash and XC18V00 families of flash memory configuration PROMs devices. Affected part numbers are included in Table 2 below.

Table 2: **Affected Products**

| Platform Flash Family | | | |
|-----------------------|------------------|-----------------|-----------------|
| XCF01SVO20C | XCF04SVO20C | XCF16PFS48C | XCF32PFS48C |
| XCF01SVO20C0100 | XCF04SVO20C0100 | XCF16PFS48C0973 | XCF32PFS48C0973 |
| XCF01SVO20C0936 | XCF04SVO20C0936 | XCF16PFS48C | XCF32PFS48C |
| XCF01SVOG20C | XCF04SVOG20C | XCF16PVO48C | XCF32PVO48C |
| XCF01SVOG20C0100 | XCF04SVOG20C0100 | XCF16PVO48C0973 | XCF32PVO48C0973 |
| XCF01SVOG20C0936 | XCF04SVOG20C0936 | XCF16PVO48C | XCF32PVO48C |
| XCF02SVO20C | XCF08PFS48C | | |
| XCF02SVO20C0100 | XCF08PFS48C0973 | | |
| XCF02SVO20C0936 | XCF08PFS48C | | |
| XCF02SVOG20C | XCF08PVO48C | | |
| XCF02SVOG20C0100 | XCF08PVO48C0973 | | |
| XCF02SVOG20C0936 | XCF08PVO48C | | |

Table 2 (Continued): Affected Products

| XC18V00 Family | | | |
|--------------------|-------------------|-------------------|-------------------|
| XC18V512PC20C | XC18V01PC20C | XC18V02PC44C | XC18V04PC44C |
| XC18V512PC20C0936 | XC18V01PC20C0100 | XC18V02PC44C0100 | XC18V04PC44C0100 |
| XC18V512PCG20C | XC18V01PC20C0936 | XC18V02PC44C0936 | XC18V04PC44C0936 |
| XC18V512PCG20C0936 | XC18V01PCG20C | XC18V02PCG44C | XC18V04PCG44C |
| XC18V512SO20C | XC18V01PCG20C0100 | XC18V02PCG44C0100 | XC18V04PCG44C0936 |
| XC18V512SO20C0100 | XC18V01PCG20C0936 | XC18V02PCG44C0936 | XC18V04VQ44C |
| XC18V512SO20C0936 | XC18V01SO20C | XC18V02VQ44C | XC18V04VQ44C0100 |
| XC18V512SOG20C | XC18V01SO20C0100 | XC18V02VQ44C0100 | XC18V04VQ44C0936 |
| XC18V512SOG20C0936 | XC18V01SO20C0936 | XC18V02VQ44C0936 | XC18V04VQG44C |
| XC18V512VQ44C | XC18V01SOG20C | XC18V02VQG44C | XC18V04VQG44C0936 |
| XC18V512VQ44C0936 | XC18V01SOG20C0100 | XC18V02VQG44C0936 | |
| XC18V512VQG44C | XC18V01SOG20C0936 | | |
| XC18V512VQG44C0936 | XC18V01VQ44C | | |
| | XC18V01VQ44C0100 | | |
| | XC18V01VQ44C0936 | | |
| | XC18V01VQG44C | | |
| | XC18V01VQG44C0936 | | |

Key Date and Cross Shipping Information for All Parts

No new production material is expected to be produced at the M5 facility. Upon availability of production units from the Fab2 facility, and no earlier than 90 days from the release date of this notice, customers may receive devices fabricated by either the Fab2 or M5 facilities until all inventory from the M5 facility is depleted.

Traceability

Platform Flash (XCF) Devices

All Platform devices manufactured at Fab2 will have different topside marking than devices manufactured at M5 fabrication facility. Table 3 below summarizes the marking changes for all devices in the Platform Flash family.

Table 3: Affected Devices in Platform Flash (XCF) Family

| Device | Package(s) | Marking Change |
|--------|------------|----------------|
| XCF01S | All | Yes |
| XCF02S | All | Yes |
| XCF04S | All | Yes |
| XCF08P | All | Yes |
| XCF16P | All | Yes |
| XCF32P | All | Yes |

The topside marking will be changed from 'RT' to 'TT' for the FS48 and VO48 packages. For smaller package VO20 without process code on the top mark, the suffix "VS" will be added to the new marking for the VO20 package. Please refer to Figure 1 and 2 below for an illustration of topside marking changes.

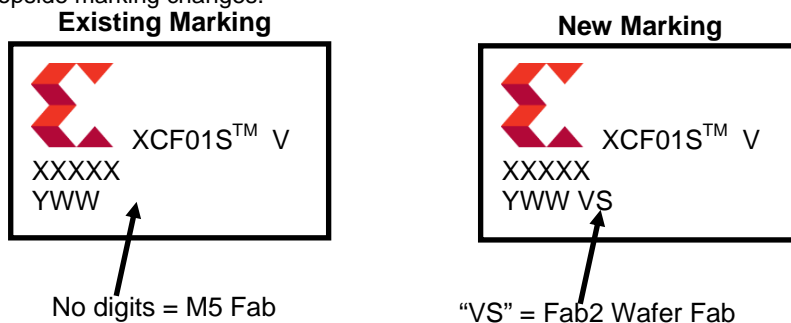


Figure 1: Sample Marking for Fabrication Change for XCF01S Device in VO20 Package

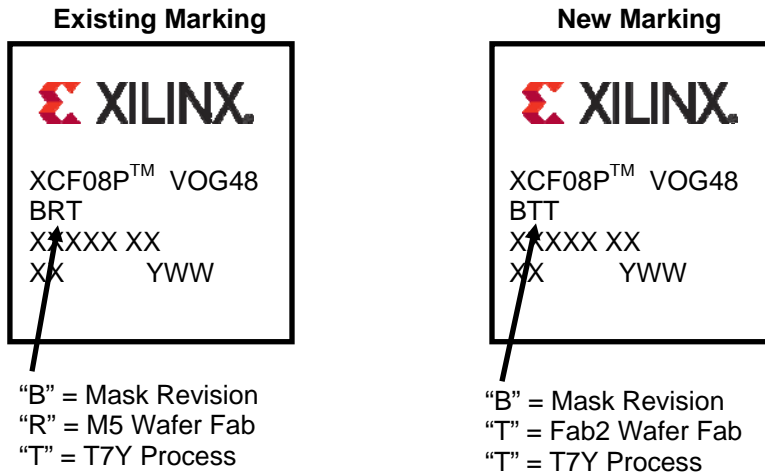


Figure 2: **Sample Marking for Fabrication Change for XCF08P Device in VOG48 Package**

XC18V00 Family Devices

All the XC18V00 devices manufactured at Fab2 facility will have a different topside mark than devices manufactured at M5 facility. Table 4 summarizes the marking changes for XC18V00 family devices.

Table 4: **Affected Devices in XC18V00 Flash Family**

| Device | Package(s) | Marking Change |
|----------|------------|----------------|
| XC18V512 | All | Yes |
| XC18V01 | All | Yes |
| XC18V02 | All | Yes |
| XC18V04 | All | Yes |

The topside marking will be changed from 'BRT' to 'BTT' for all the packages. An example for XC18V01 PC20 package is shown in Figure 3 below.

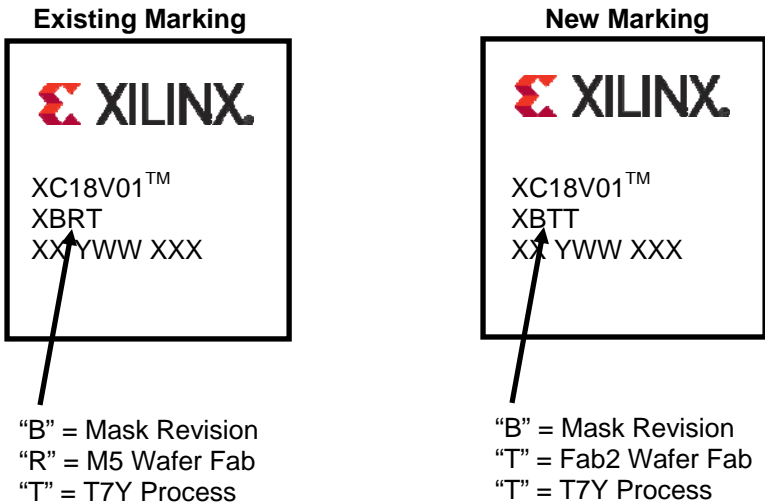


Figure 3: **Sample Marking for Fabrication Change for XC18V01 Device in PC20 Package**

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (<http://www.xilinx.com/support>). Register today and personalize your “MyAlerts” area to include Customer Notifications. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to [Xilinx Answer Record 18683](#).

Additional Documentation

Qualification Report (RPT142):

<https://secure.xilinx.com/webreg/clickthrough.do?cid=139884>

Revision History

The following table shows the revision history for this document.

| Date | Version | Revision |
|----------|---------|---|
| 09/21/09 | 1.0 | Initial release. |
| 10/05/09 | 1.1 | Added Tape & Reel SCD0100 parts to Table 2 Affected Products list |

Disclaimer

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